

SOLDER ALLOY, SOLDER BALL, SOLDER PASTE, AND SOLDER JOINT**ABSTRACT**

Provided are a solder a solder alloy, a solder ball, a solder paste, and a solder joint,
5 which have a low melting point, high hardness in a high-temperature environment, heat cycle
resistance, and electromigration resistance. The solder alloy has an alloy composition
consisting of, by mass%, Bi: 30 to 60%, Ag: 0.7 to 2.0%, Cu: more than 0% and 1.00% or less,
Ni: 0.01 to 1.00%, Sb: 0.2 to 1.5%, with the balance being Sn.

10 [No Figure]